Transistors

2SA1767

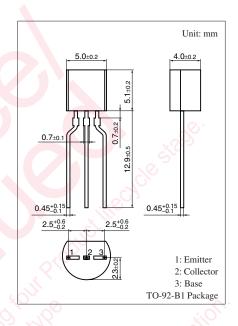
Silicon PNP epitaxial planar type

For general amplification Complementary to 2SC1473A

Features

 \bullet High collector-emitter voltage (Base open) $V_{\mbox{CEO}}$

Absolute Maximum Ratings $T_a = 25^{\circ}C$						
Parameter	Symbol	Rating	Unit			
Collector-base voltage (Emitter open)	V _{CBO}	-300	V			
Collector-emitter voltage (Base open)	V _{CEO}	-300	V			
Emitter-base voltage (Collector open)	V _{EBO}	-5	V			
Collector current	I _C	-70	mA			
Peak collector current	I _{CP}	-100	mA			
Collector power dissipation	P _C	750	mW			
Junction temperature	Tj	150	°C			
Storage temperature	T _{stg}	-55 to +150	°C			



Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

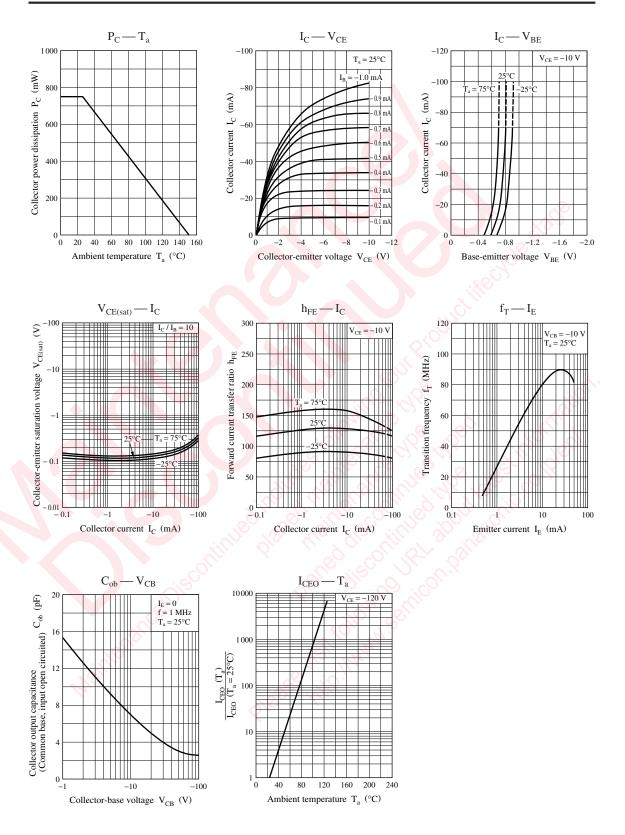
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -100 \ \mu A, \ I_{\rm B} = 0$	-300	8		V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = -1 \ \mu A, \ I_{\rm C} = 0$	-5			V
Forward current transfer ratio *	h _{FE}	$V_{CE} = -10 \text{ V}, I_C = -5 \text{ mA}$	30		150	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -10 \text{ mA}, I_{\rm B} = -1 \text{ mA}$			- 0.6	V
Transition frequency	f _T	$V_{CB} = -10 \text{ V}, I_E = 10 \text{ mA}, f = 200 \text{ MHz}$		50		MHz
Collector output capacitance	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		7		pF
(Common base, input open circuited)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	Р	Q
h _{FE}	30 to 100	60 to 150

Panasonic



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